# MA4X193 (MA193)

### Silicon epitaxial planar type

#### For switching circuit

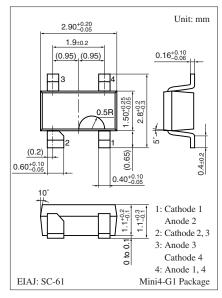
#### ■ Features

- Four isolated elements contained in one package
- Short reverse recovery time t<sub>rr</sub>
- Bridge diodes for surface mounting
- Anode common + cathode common composite product

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Repetitive peak reverse voltage	$V_{RRM}$	80	V
Forward current (Average)	I <sub>F(AV)</sub>	70	mA
Repetitive peak forward current	$I_{FRM}$	150	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	250	mA
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

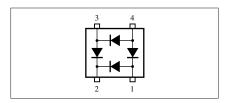
Note) \*: t = 1 s



Marking Symbol: M2Z

#### Internal Connection

Note) The part number in the parenthesis shows conventional part number.

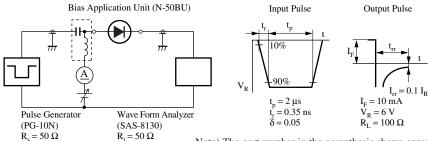


#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

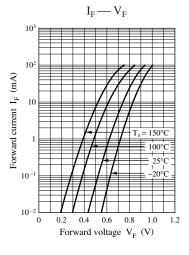
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_F$	$I_F = 70 \text{ mA}$			1.2	V
Reverse voltage	V <sub>R</sub>	$I_R = 100 \mu A$	80			V
Reverse current	$I_R$	$V_R = 75 \text{ V}$			100	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$			15	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

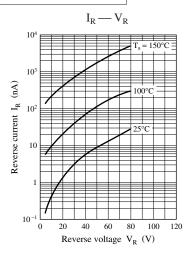
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

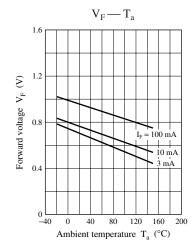
- 2. Absolute frequency of input and output is 100 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit

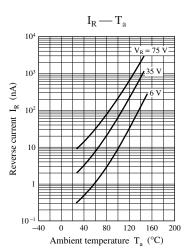


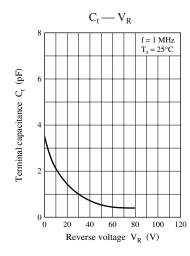
#### 4-1 and 4-3 pins (anode common) characteristics charts

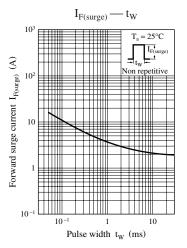








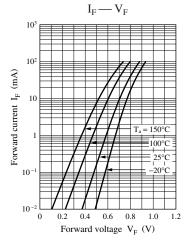


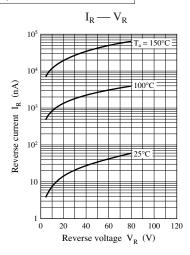


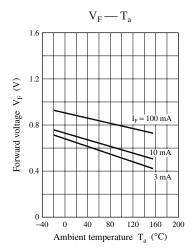
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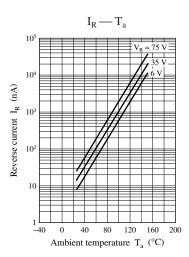
## **Panasonic**

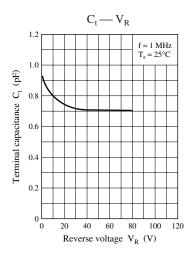
#### 1-2 and 3-2 pins (cathode common) characteristics charts

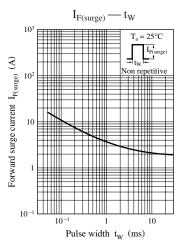












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